

### Major Ratings and Characteristics

$I_{F(AV)}$	0.5A , 0.8A
$V_{RRM}$	50-1000V
$I_{FSM}$	35 A
$I_R$	5.0 $\mu$ A
$V_F$	1.0V
$T_j$ max.	150 °C

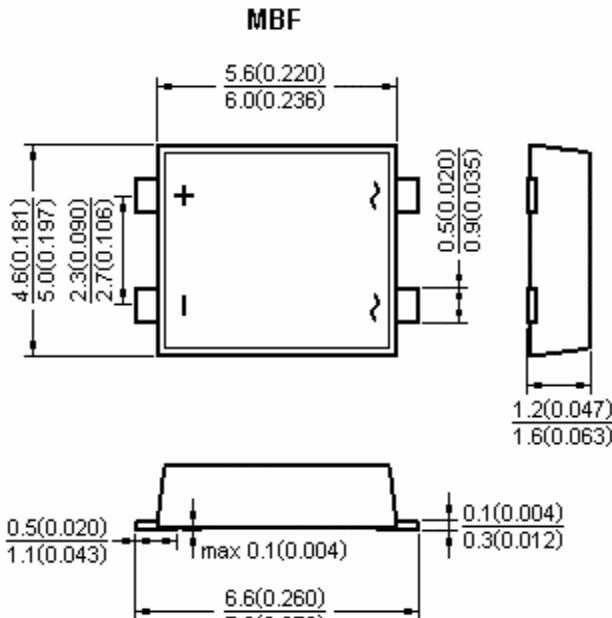


### Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC

### Mechanical Data

- Case: MBF Molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Polarity symbols marked on body



Dimensions in millimeters and (inches)

### Maximum Ratings & Thermal Characteristics & Electrical Characteristics

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

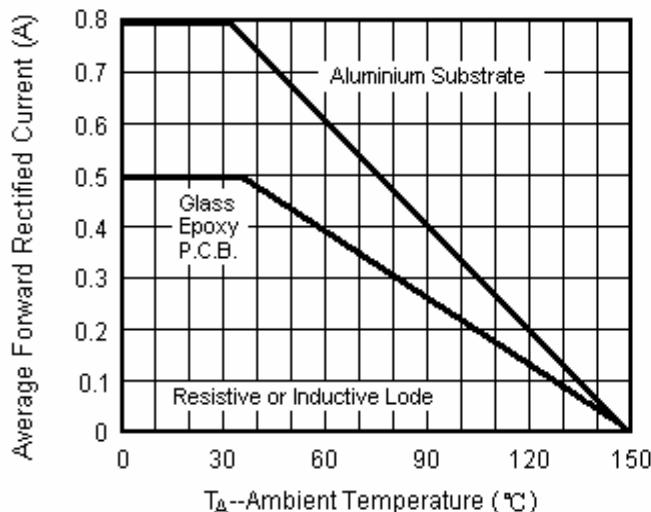
	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward output rectified current at $T_A=30^\circ\text{C}$ -on glass-epoxy P.C.B.(NOTE 1) -on aluminum substrate(NOTE 2)	$I_{F(AV)}$				0.5				A
					0.8				
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load(JEDEC Method)	$I_{FSM}$				35				A
Maximum instantaneous forward voltage drop per leg at 0.4A	$V_F$				1				V
Maximum DC reverse current at $T_A = 25^\circ\text{C}$ rated DC blocking voltage per leg $T_A = 125^\circ\text{C}$	$I_R$				5.0				$\mu\text{A}$
					100				
Typical junction capacitance per leg at 4.0 V ,1MHz	$C_J$				13				p F
Thermal resistance per leg (NOTE 1) (NOTE 2) (NOTE 1)	$R_{\theta JA}$				85				$^\circ\text{C}/\text{W}$
	$R_{\theta JA}$				70				
	$R_{\theta JL}$				20				
Operating junction and storage temperature range	$T_j, T_{STG}$				-55 to +150				°C

NOTE1:On glass epoxy P.C.B. mounted on 0.05×0.05" (1.3×1.3mm) pads

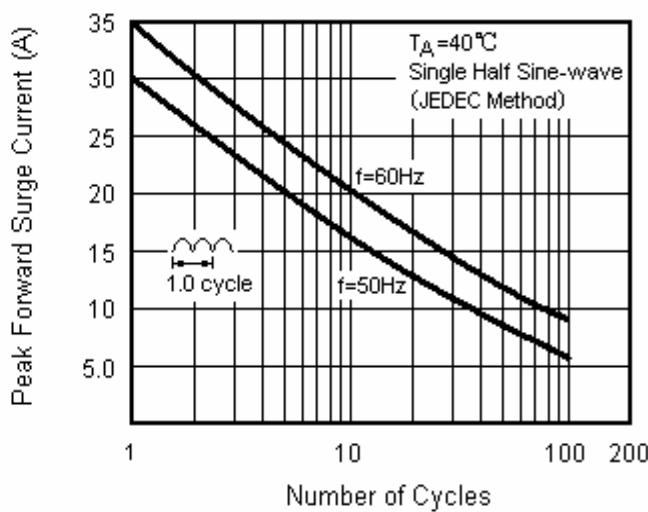
NOTE2:On aluminum substrate P.C.B. with an area of 0.8" × 0.8" (20×20mm) mounted on 0.05×0.05" (1.3×1.3mm) solder pad

**Characteristic Curves ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

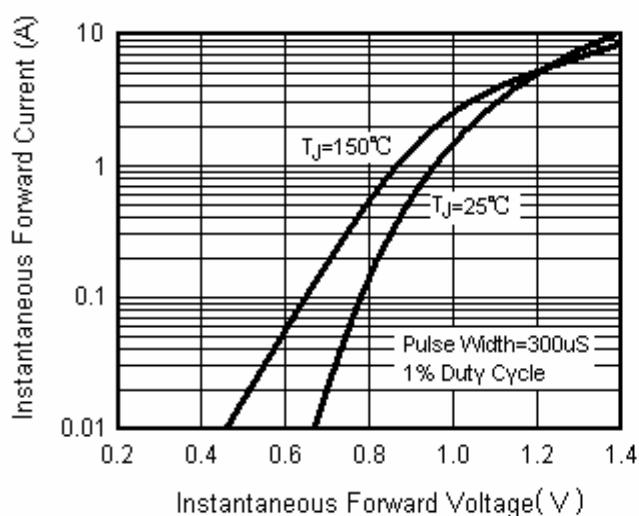
**Fig.1 Derating Curve For Output Rectified Current**



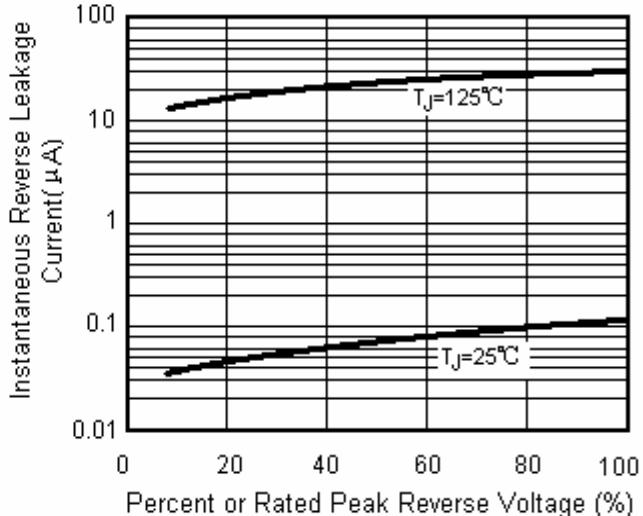
**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current Per Leg**



**Fig.3 Typical Forward Voltage Characteristics Per Leg**



**Fig.4 Typical Reverse Leakage Characteristics Per Leg**



**Fig.5 Typical Junction Capacitance Per Leg**

